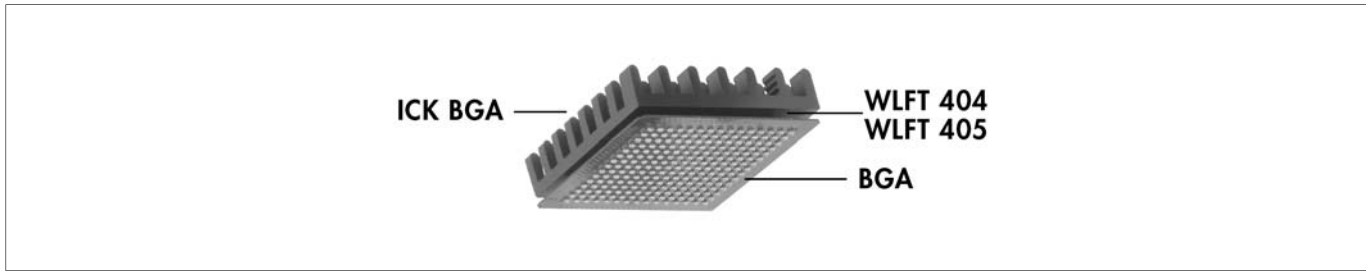


Heatsinks for BGAs



- particularly suited for **B**all **G**rid **A**rrays
 - heatsink dimensions match the respective BGA-type
 - can be glued directly on the BGA component
- surface:** black anodised

art. no.			
ICK BGA 10 x 10 WLF ... 10 x 10			
ICK BGA 10 x 10 x 10 WLF ... 10 x 10			
ICK BGA 14 x 14 WLF ... 14 x 14			
ICK BGA 14 x 14 x 10 WLF ... 14 x 14			
ICK BGA 21 x 21 WLF ... 21 x 21			

Thermal conduct. foil WLFT 404/405 → E 5
Thermal conductive glue → E 15
Thermal conductive paste → E 13
Processor overview → B 2 - 7

SMD-heatsinks → B 38 - 40
Mounting material for semiconduct. → E 37 - 41
Hole pattern → A 21
Technical introduction → A 2 - 7

A

Heatsinks for BGAs

B

C

D

E

F

G

H

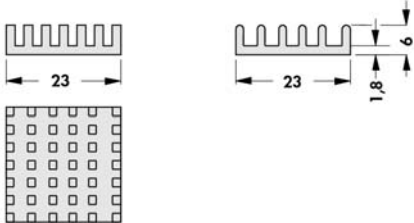
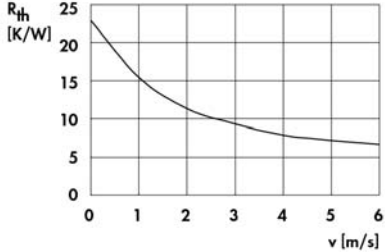
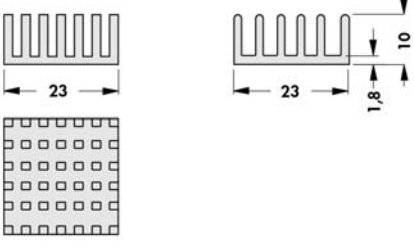
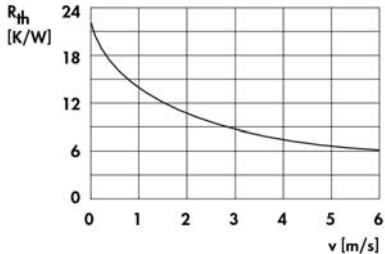
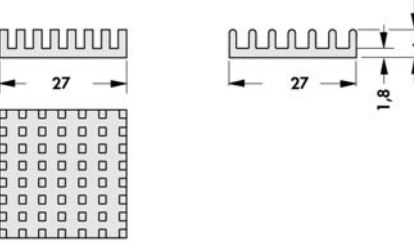
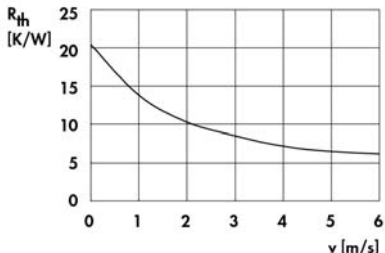
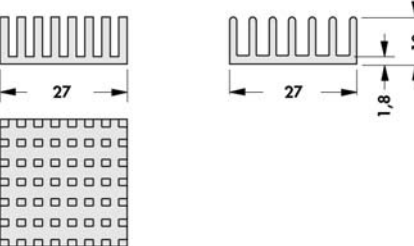
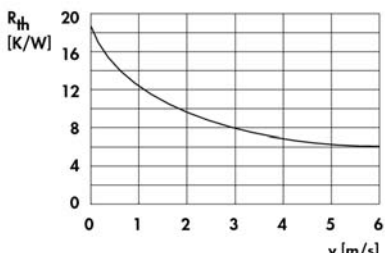
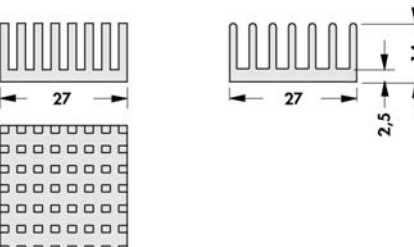
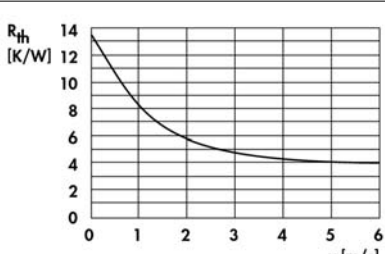
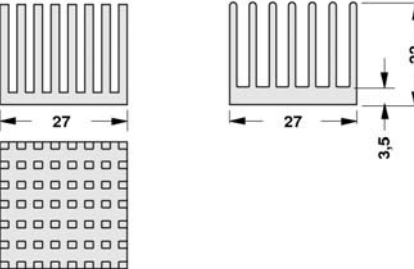
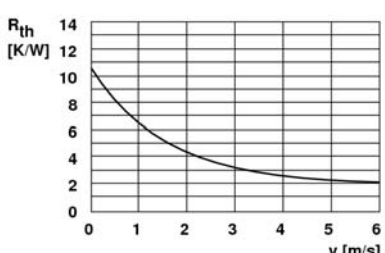
I

K

L

M

N

art. no. ICK BGA 23 x 23 WLF ... 23 x 23		
art. no. ICK BGA 23 x 23 x 10 WLF ... 23 x 23		
art. no. ICK BGA 27 x 27 WLF ... 27 x 27		
art. no. ICK BGA 27 x 27 x 10 WLF ... 27 x 27		
art. no. ICK BGA 27 x 27 x 14 WLF ... 27 x 27		
art. no. ICK BGA 27 x 27 x 22 WLF ... 27 x 27		

B 17

Thermal conduct. foil WLFT 404/405 → E 5
 Thermal conductive glue → E 15
 Thermal conductive paste → E 13
 Processor overview → B 2 - 7

SMD-heatsinks → B 38 - 40
 Mounting material for semiconduct. → E 37 - 41
 Hole pattern → A 21
 Technical introduction → A 2 - 7